

NB4N111K

3.3V Differential In 1:10 Differential Fanout Clock Driver with HCSL Level Output

Description

The NB4N111K is a differential input clock 1 to 10 HCSL fanout buffer, optimized for ultra low propagation delay variation. The NB4N111K is designed with HCSL clock distribution for FBDIMM applications in mind.

Inputs can accept differential LVPECL, CML, or LVDS levels. Single-ended LVPECL, CML, LVCMS or LVTTL levels are accepted with the proper V_{REFAC} supply (see Figures 5, 10, 11, 12, and 13). Clock input pins incorporate an internal 50 Ω on die termination resistors. Outputs can interface with LVDS with proper termination (See Figure 15).

The NB4N111K specifically guarantees low output-to-output skews. Optimal design, layout, and processing minimize skew within a device and from device to device. System designers can take advantage of the NB4N111K's performance to distribute low skew clocks across the backplane or the motherboard.

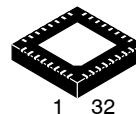
Features

- Typical Input Clock Frequencies: 100, 133, 166, 200, 266, 333, and 400 MHz
- 340 ps Typical Rise and Fall Times
- 800 ps Typical Propagation Delay
- Δtpd 100 ps Maximum Propagation Delay Variation Per Each Differential Pair
- <1 ps RMS Additive Clock jitter
- Operating Range: V_{CC} = 3.0 V to 3.6 V with V_{EE} = 0 V
- Differential HCSL Output Level or LVDS with Proper Termination
- These are Pb-Free Devices



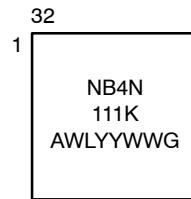
ON Semiconductor®

<http://onsemi.com>



QFN32
MN SUFFIX
CASE 488AM

MARKING DIAGRAM*



A	= Assembly Site
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb-Free Package

*For additional marking information, refer to Application Note AND8002/D.

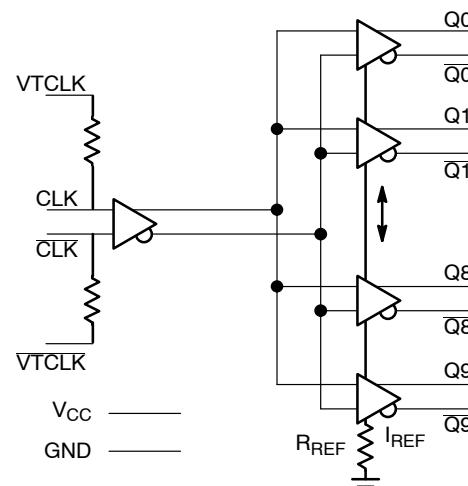


Figure 1. Pin Configuration (Top View)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

NB4N111K

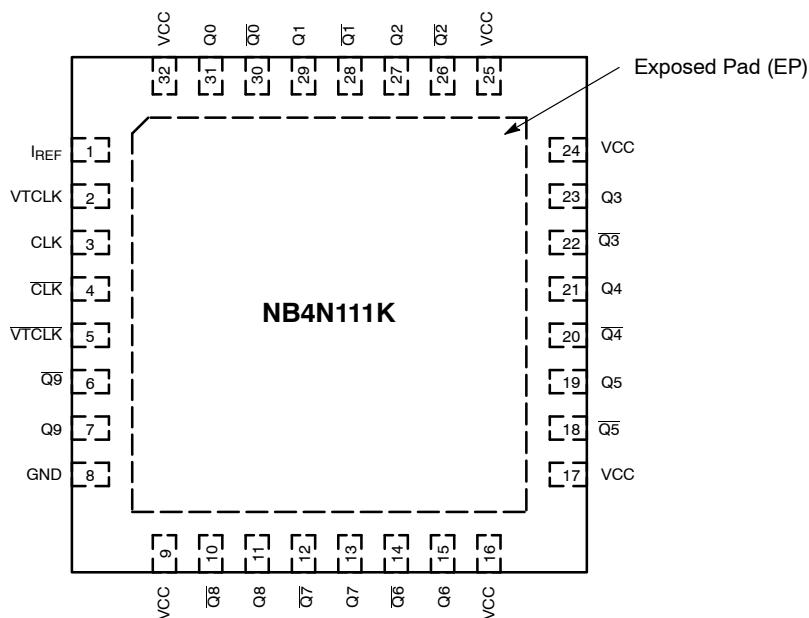


Figure 2. Pinout Configuration (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Description
1	I _{REF}	Output	Output current programming pin. Connect to GND. (See Figure 9).
2, 5	VTCLK, VTCLK	-	Internal 50 Ω Termination Resistor connection Pins. In the differential configuration when the input termination pins are connected to the common termination voltage, and if no signal is applied then the device may be susceptible to self-oscillation.
3	CLK	LVPECL Input	CLOCK Input (TRUE)
4	CLK	LVPECL Input	CLOCK Input (INVERT)
8	GND	-	Supply Ground. GND pin must be externally connected to power supply to guarantee proper operation.
9, 16, 17, 24, 25, 32	V _{CC}	-	Positive Supply pins. V _{CC} pins must be externally connected to a power supply to guarantee proper operation.
6, 10, 12, 14, 18, 20, 22, 26, 28, 30	Q[09-0]	HCSL or LVDS Output	Noninverted Clock Output. (For LVDS levels see Figure 15)
7, 11, 13, 15, 19, 21, 23, 27, 29, 31	Q[09-0]	HCSL or LVDS Output	Inverted Clock Output. (For LVDS levels see Figure 15)
Exposed Pad	EP	GND	Exposed Pad. The thermally exposed pad (EP) on package bottom (see case drawing) must be attached to a sufficient heat-sinking conduit for proper thermal operation. (Note 1)

1. The exposed pad must be connected to the circuit board ground.

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Table 2. ATTRIBUTES

Characteristic	Value
Input Default State Resistors	None
ESD Protection	Human Body Model
Moisture Sensitivity (Note 2)	QFN32
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	622
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

2. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS (Note 3)

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	GND = 0 V		6.0	V
V _I	Positive Input	GND = 0 V		GND – 0.3 ≤ V _I ≤ V _{CC}	V
V _{INPP}	Differential Input Voltage	CLK – $\overline{\text{CLK}}$		V _{CC}	V
I _{OUT}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range	QFN32		-40 to +70	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient) (Note 3)	0 lfpm 500 lfpm	QFN32 QFN32	31 27	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	2S2P (Note 4)	QFN32	12	°C/W
T _{sol}	Wave Solder	Pb-Free		265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

3. JEDEC standard 51–6, multilayer board – 2S2P (2 signal, 2 power).

4. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

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Table 4. DC CHARACTERISTICS (V_{CC} = 3.0 V to 3.6 V, T_A = –40°C to +70°C Note 5)

Symbol	Characteristic	Min	Typ	Max	Unit
I_{GND}	GND Supply Current (All Outputs Loaded)	70	98	120	mA
I_{CC}	Power Supply Current (All Outputs Loaded)			300	mA
I_{IH}	Input HIGH Current CLKx, \overline{CLKx}		2.0	150	μA
I_{IL}	Input LOW Current CLKx, \overline{CLKx}	–150	–2.0		μA

DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED (Figures 5 and 7)

V_{th}	Input Threshold Reference Voltage Range (Note 6)	1050		$V_{CC} - 150$	mV
V_{IH}	Single-Ended Input HIGH Voltage	$V_{th} + 150$		V_{CC}	mV
V_{IL}	Single-Ended Input LOW Voltage	GND		$V_{th} - 150$	mV

DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY (Figures 6 and 8)

V_{IHD}	Differential Input HIGH Voltage	1200		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	GND		$V_{CC} - 75$	mV
V_{ID}	Differential Input Voltage ($V_{IHD} - V_{ILD}$)	75		2400	mV
V_{CMR}	Input Common Mode Range	1163		$V_{CC} - 75$	

HCSL OUTPUTS (Figure 4)

V_{OH}	Output HIGH Voltage	600	740	900	mV
V_{OL}	Output LOW Voltage	–150	0	150	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input parameters vary 1:1 with V_{CC} . Measurements taken with all outputs loaded 50 Ω to GND, see Figure 9.

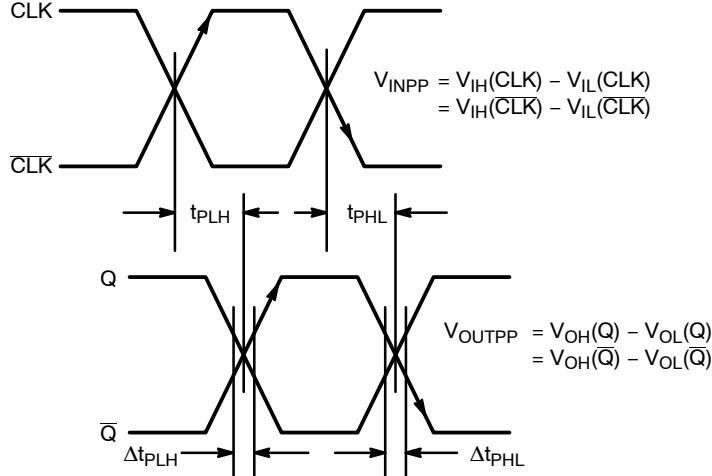
6. V_{th} is applied to the complementary input when operating in single ended mode.

Table 5. AC CHARACTERISTICS $V_{CC} = 3.0 \text{ V}$ to 3.6 V , $GND = 0 \text{ V}$; -40°C to $+70^\circ\text{C}$ (Note 7)

Symbol	Characteristic		Min	Typ	Max	Unit
V_{OUTPP}	Output Voltage Amplitude (@ $V_{INPPmin}$)	$f_{in} = 400 \text{ MHz}$		725	1000	mV
t_{PLH}, t_{PHL}	Propagation Delay to (See Figure 3)	CLK/CLK to Qx/ \overline{Qx}	550	800	1100	ps
$\Delta t_{PLH}, \Delta t_{PHL}$	Propagation Delay Variations Variation Per Each Diff Pair CLK/CLK to Qx/ \overline{Qx} (Note 8) (See Figure 3)			100		ps
t_{SKW}	Duty Cycle Skew (Note 9) Within-Device Skew Device-to-Device Skew (Note 10)			20 100 150		ps ps ps
t_{JITTER}	RMS Random Clock Jitter (Note 11)	$f_{in} = 400 \text{ MHz}$		1		ps
V_{cross}	Absolute Crossing Magnitude Voltage		250		550	mV
ΔV_{cross}	Variation in Magnitude of V_{cross}			150		mV
t_r, t_f	Absolute Magnitude in Output Risetime and Falltime	Qx, \overline{Qx}	175	340	700	ps
$\Delta t_r, \Delta t_f$	Variation in Magnitude of Risetime and Falltime (Single-Ended)	Qx, \overline{Qx}			125	ps
	(See Figure 4)					

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

7. Measured by forcing V_{INPP} (MIN) from a 50% duty cycle clock source. Measurements taken with all outputs loaded 50Ω to GND, see Figure 9. Typical gain is 20 dB.
8. Measured from the input pair crosspoint to each single output pair crosspoint across temp and voltage ranges.
9. Duty cycle skew is measured between differential outputs using the deviations of the sum of T_{pw-} and T_{pw+} .
10. Skew is measured between outputs under identical transition @ 400 MHz.
11. Additive RMS jitter with 50% duty cycle clock signal using phase noise integrated from 12 KHz to 33 MHz

**Figure 3. AC Reference Measurement**

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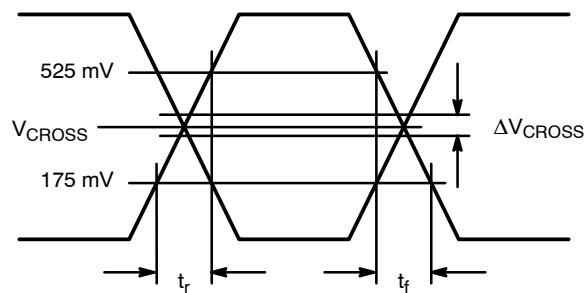


Figure 4. HCSL Output Parameter Characteristics

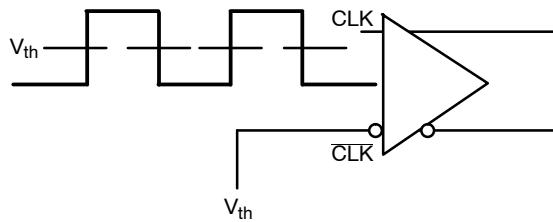


Figure 5. Differential Input Driven Single-Ended ($V_{th} = V_{REFAC}$)

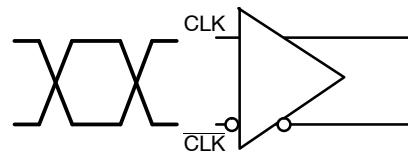


Figure 6. Differential Inputs Driven Differentially

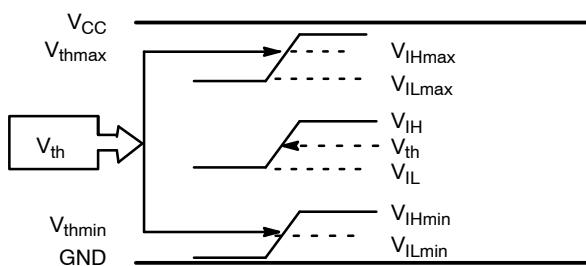


Figure 7. V_{th} Diagram

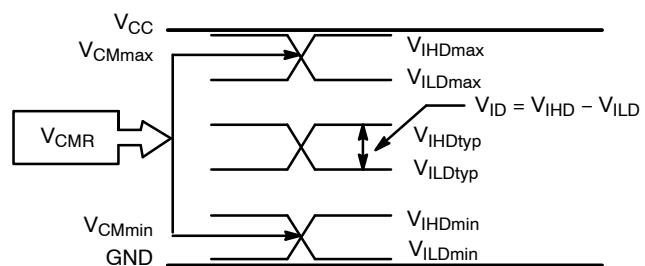
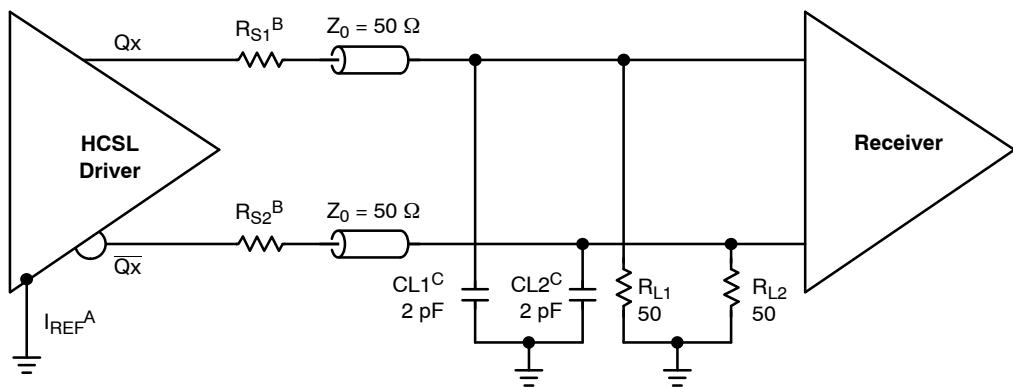
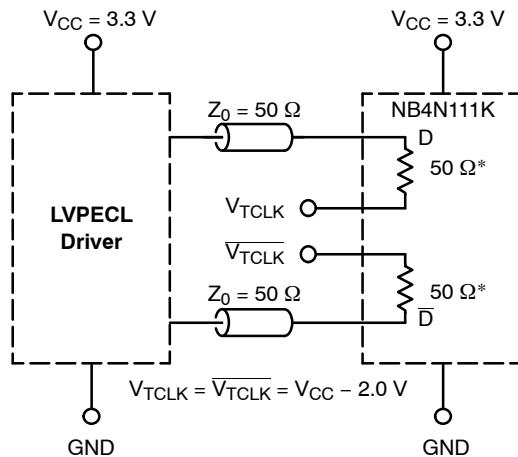


Figure 8. V_{CMR} Diagram

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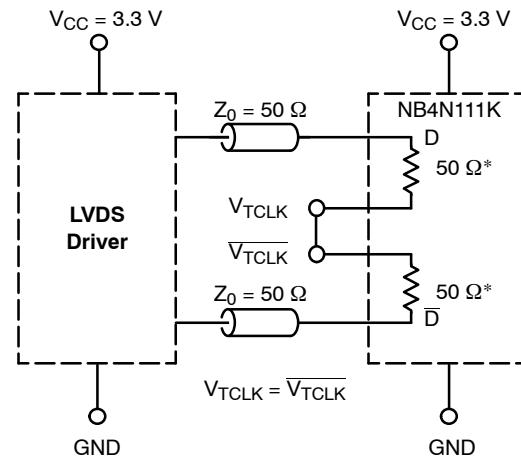


**Figure 9. Typical Termination Configuration for Output Driver and Device Evaluation
 C_{LX} for Test Only (Representing Receiver Input Loading); Not Added to Application**



*RTIN, Internal Input Termination Resistor

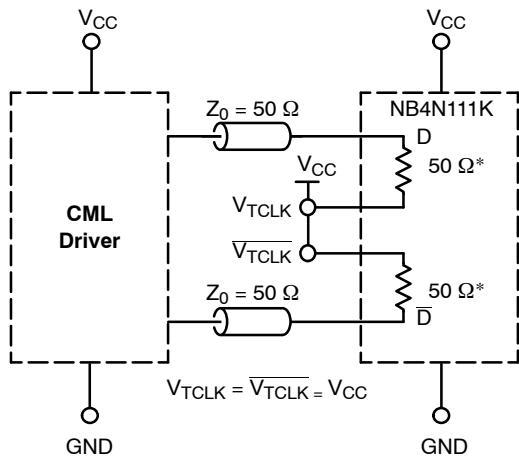
Figure 10. LVPECL Interface



*RTIN, Internal Input Termination Resistor

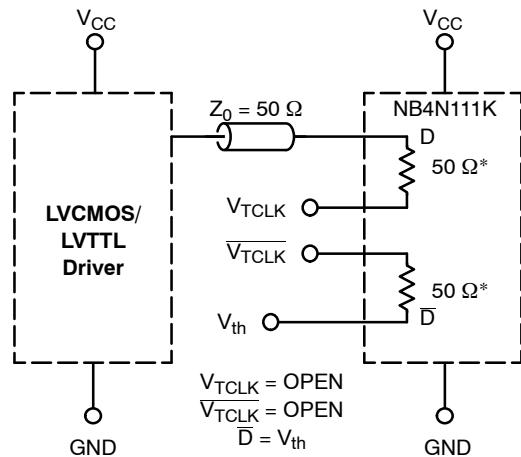
Figure 11. LVDS Interface

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*RTIN, Internal Input Termination Resistor

Figure 12. Standard 50 Ω Load CML Interface



*RTIN, Internal Input Termination Resistor

Figure 13. LVCMS/LVTTL Interface

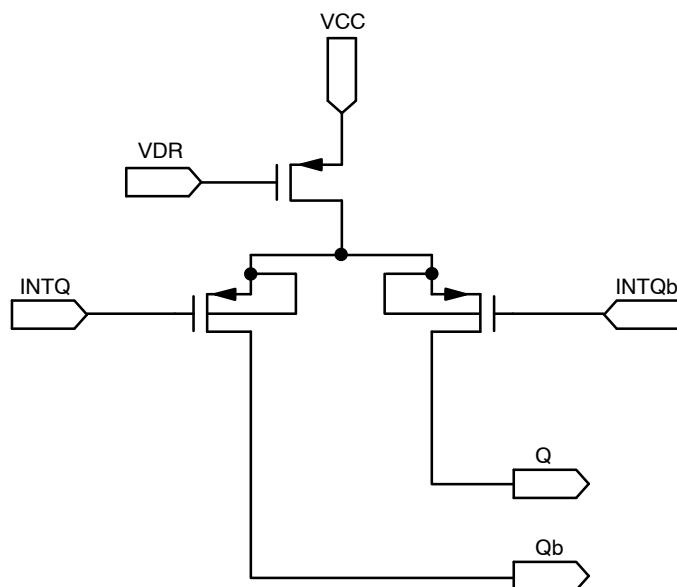


Figure 14. HCSL Output Structure

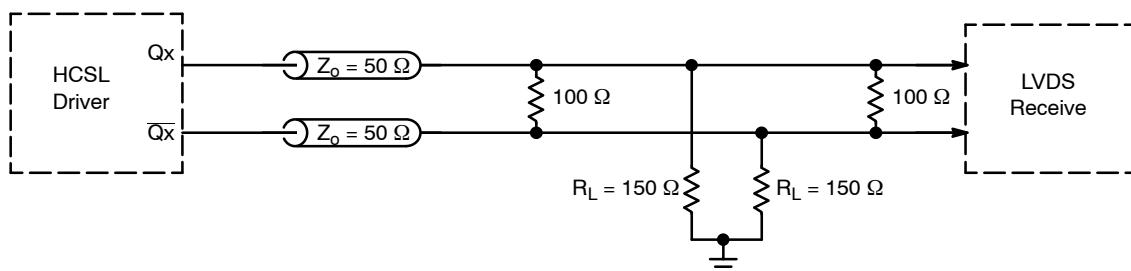


Figure 15. HCSL Interface Termination to LVDS

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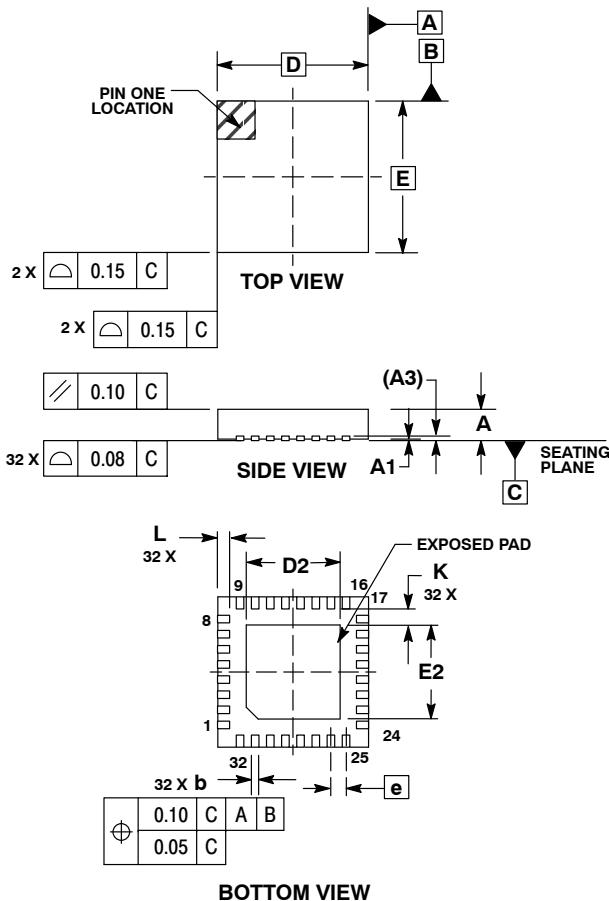
ORDERING INFORMATION

Device	Package	Shipping[†]
NB4N111KMNG	QFN32 (Pb-Free)	79 Units / Rail
NB4N111KMNR4G	QFN32 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

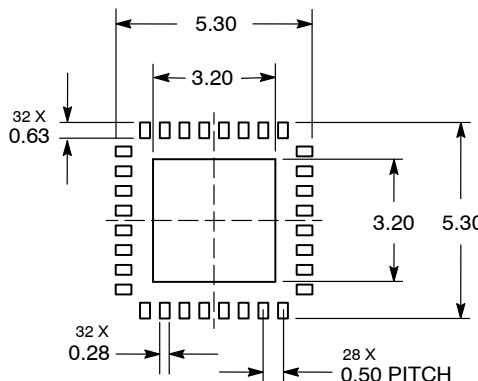
PACKAGE DIMENSIONS

QFN32 5x5, 0.5P
CASE 488AM-01
ISSUE O



- NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM TERMINAL
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.800	0.900	1.000
A1	0.000	0.025	0.050
A3	0.200	REF	
b	0.180	0.250	0.300
D	5.00	BSC	
D2	2.950	3.100	3.250
E	5.00	BSC	
E2	2.950	3.100	3.250
e	0.500	BSC	
K	0.200	---	---
L	0.300	0.400	0.500

SOLDERING FOOTPRINT*

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

The products described herein (NB4N111k), may be covered by U.S. patents including 6,362,644. There may be other patents pending.

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- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
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- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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